# BC818-40LT1G

# **General Purpose Transistors**

# NPN Silicon

### Features

• These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage	V <sub>CEO</sub>	25	V
Collector – Base Voltage	V <sub>CBO</sub>	30	V
Emitter-Base Voltage	V <sub>EBO</sub>	5.0	V
Collector Current – Continuous	Ι <sub>C</sub>	500	mAdc

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit		
Total Device Dissipation FR-5 Board, (Note 1) $T_A = 25^{\circ}C$ Derate above $25^{\circ}C$	P <sub>D</sub>	225 1.8	mW mW/°C		
Thermal Resistance, Junction-to-Ambient	$R_{\thetaJA}$	556	°C/W		
Total Device Dissipation Alumina Substrate, (Note 2) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	300 2.4	mW mW/°C		
Thermal Resistance, Junction-to-Ambient	$R_{\thetaJA}$	417	°C/W		
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C		

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

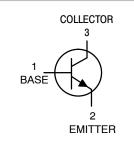
1. FR-5 =  $1.0 \times 0.75 \times 0.062$  in.

2. Alumina = 0.4 x 0.3 x 0.024 in 99.5% alumina.



## **ON Semiconductor®**

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## MARKING DIAGRAMS



6G = Specific Device Code M = Date Code\*

 = Pb-Free Package (Note: Microdot may be in either location)
\*Date Code orientation and/or overbar may

vary depending upon manufacturing location.

## **ORDERING INFORMATION**

Devi	се	Package	Shipping <sup>†</sup>
BC818-4	0LT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel

+ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# BC818-40LT1G

## **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage (I <sub>C</sub> = –10 mA)	V <sub>(BR)</sub> CEO	25	-	-	V
Collector – Emitter Breakdown Voltage ( $V_{EB}$ = 0, I <sub>C</sub> = -10 µA)	V <sub>(BR)CES</sub>	30	-	-	V
Emitter – Base Breakdown Voltage ( $I_E = -1.0 \ \mu A$ )	V <sub>(BR)EBO</sub>	5.0	-	-	V
Collector Cutoff Current $(V_{CB} = 20 V)$ $(V_{CB} = 20 V, T_A = 150^{\circ}C)$	I <sub>CBO</sub>			100 5.0	nA μA
ON CHARACTERISTICS	-				-
DC Current Gain (I <sub>C</sub> = 100 mA, V <sub>CE</sub> = 1.0 V) (I <sub>C</sub> = 500 mA, V <sub>CE</sub> = 1.0 V)	h <sub>FE</sub>	250 40		600 -	-
Collector – Emitter Saturation Voltage $(I_C = 500 \text{ mA}, I_B = 50 \text{ mA})$	V <sub>CE(sat)</sub>	-	-	0.7	V
Base – Emitter On Voltage $(I_C = 500 \text{ mA}, V_{CE} = 1.0 \text{ V})$	V <sub>BE(on)</sub>	-	-	1.2	V
SMALL-SIGNAL CHARACTERISTICS					
Current-Gain – Bandwidth Product (I <sub>C</sub> = 10 mA, V <sub>CE</sub> = 5.0 Vdc, f = 100 MHz)	f <sub>T</sub>	100	-	-	MHz
Output Capacitance (V <sub>CB</sub> = 10 V, f = 1.0 MHz)	C <sub>obo</sub>	-	10	-	pF

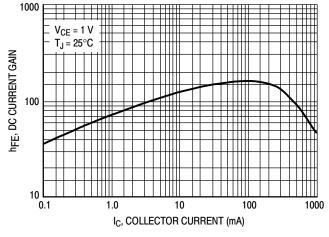
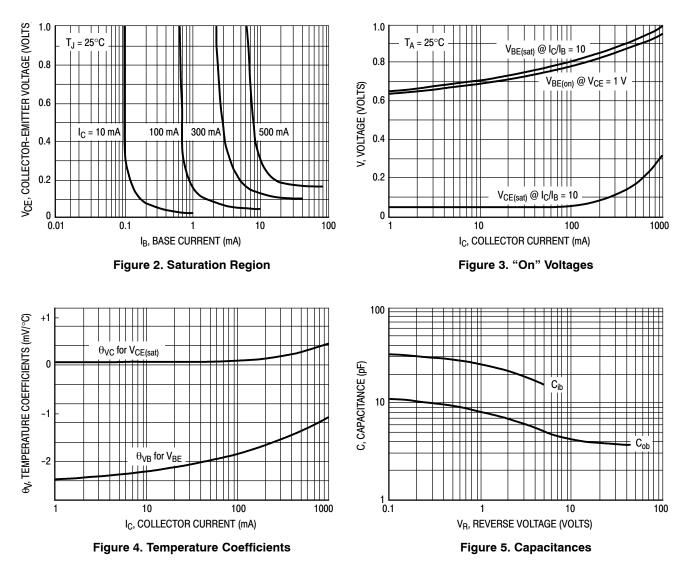


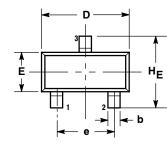
Figure 1. DC Current Gain

## BC818-40LT1G



#### PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AN** 

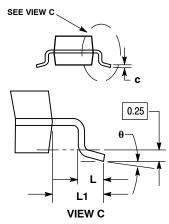


STYLE 6:

BASE PIN 1.

EMITTER 2. 3

COLLECTOR



NOTES DIMENSIONING AND TOLERANCING PER ANSI

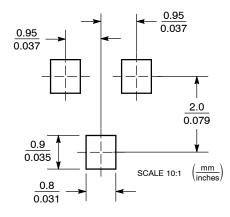
Y14.5M, 1982. CONTROLLING DIMENSION: INCH. 2.

1.

- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD З. THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD 318-08. 4.

	MILLIMETERS				INCHES	
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
С	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104

#### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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